

Conductively Coated 3D Printed Field emission arrays

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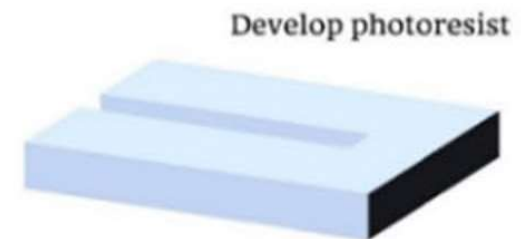
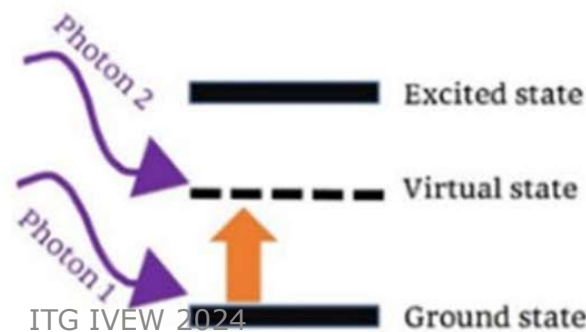
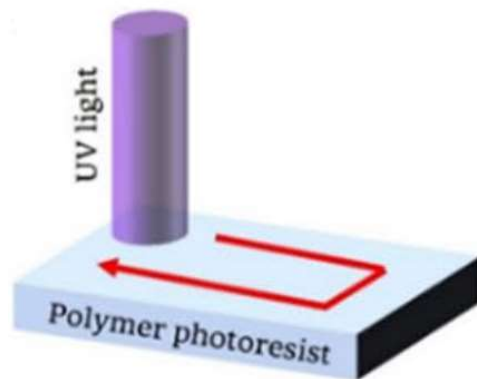


Outline

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 - Practical benefits
- Instrumentation
 - 2PP printer
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- Characterization
 - Vector VS BMP printing
 - Coating
- Field emission (FE) Experiment
- Future modifications
- Conclusions

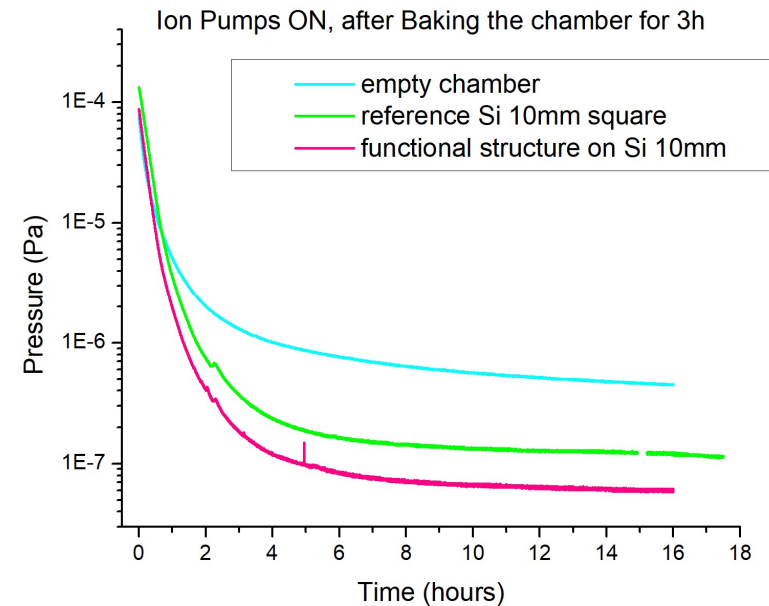
Motivation for 2PL printed FEAs – 1/2

- „Two-photon lithography (2PL) is a novel fabrication technique which, like photolithography, utilises resist and UV light to create patterns.“
- Generates 3d patterns by exposing the UV laser to areas called voxels
- Changing the laser intensity adjusts the dimension of the pattern.
- Resolution up to 50 nm IQS Nano 3D printer



Motivation for 2PL printed FEAs – 2/2

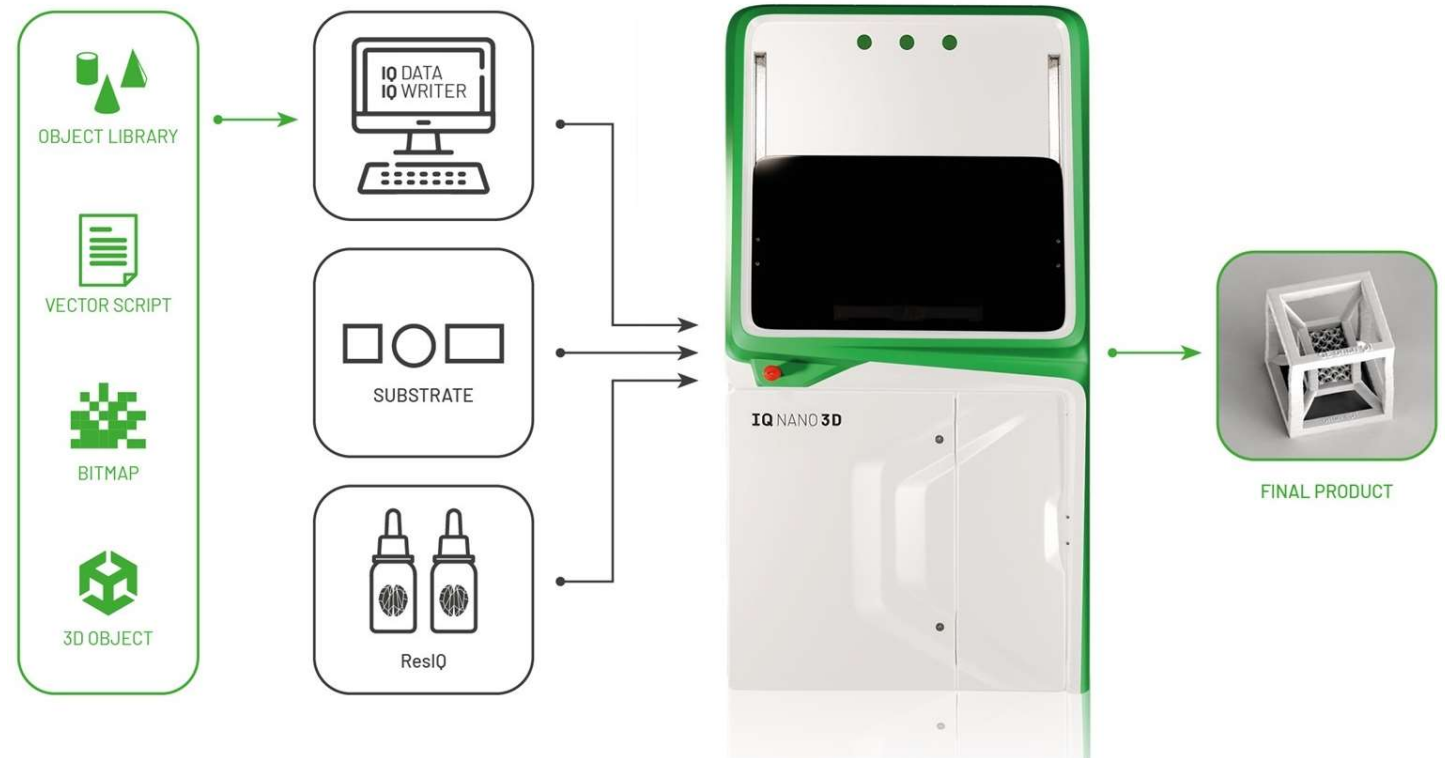
- Fast development
- Reasonable printing speeds compared to other techniques
- Affordable material cost of resin
- Resin compatible with chemical treatment, ie. $\text{H}_2\text{C}=\text{O}$ resistant
- Ultra-high vacuum compatible



D. Burda et al., "Conductively Coated 3D Printed Emitters for Electron Devices," 2024 IEEE 37th International Vacuum Nanoelectronics Conference (IVNC), Brno, Czech Republic, 2024, unpublished.

Instrumentation – 1/2

- 2PP 3D printer
 - Acousto-optic beam deflection system
 - > Very fast printing speeds
- Variable voxel size printing strategy
- Bitmap vs. Vector printing



IQS Nano 3D, <https://iqsnano.com/3d-nano-printer/>

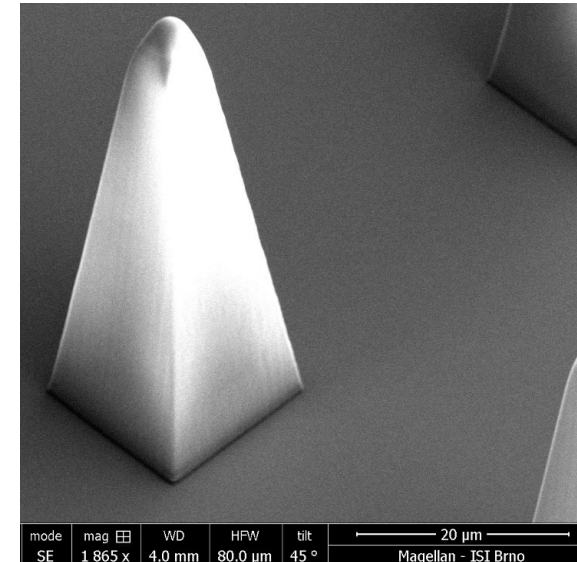
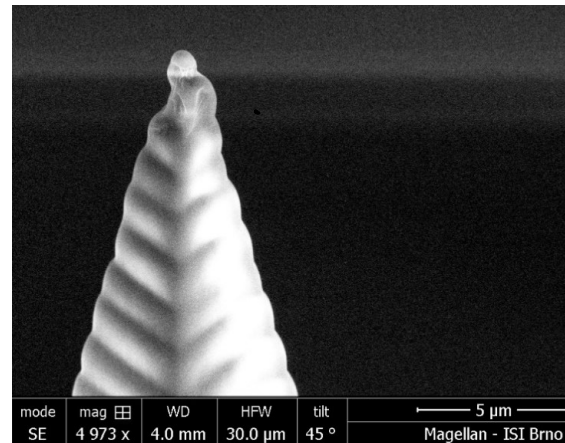
Instrumentation – 2/2

- RIE (PlasmaPro, Oxford Instruments)
 - O₂ Plasma thinning, 10s, ICP 1500W, CCP 10W
- Metallic coating
 - Magnetron Sputtering (Q150T ES, Quorum)
 - Up to 40 nm of thickness
 - Au, Cr



Characterization – 1/2

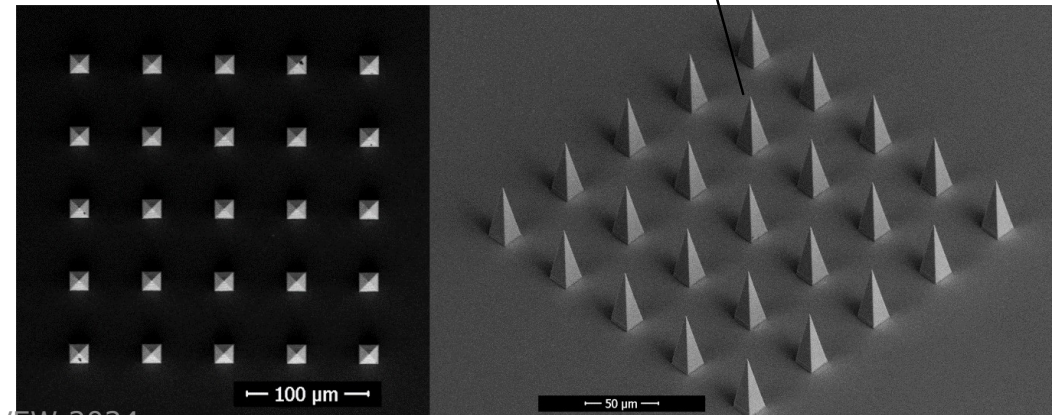
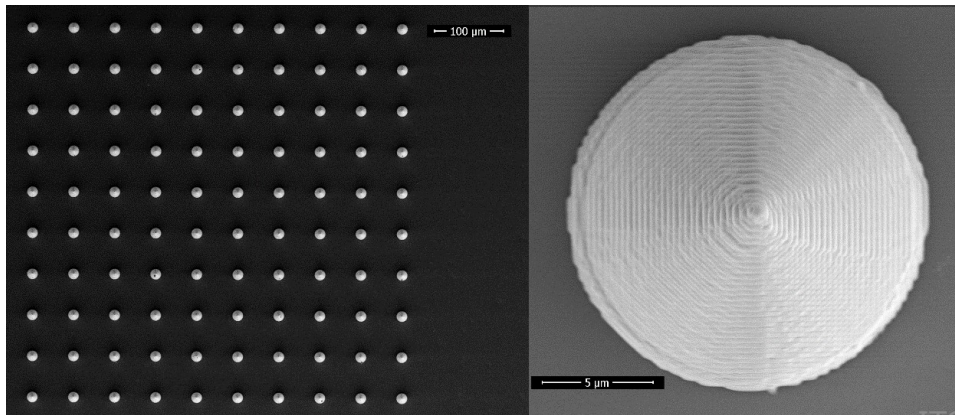
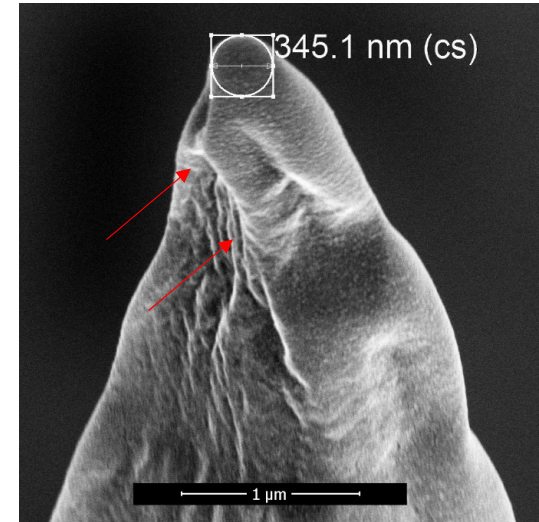
- Vector 2PP printing:
 - ✓ Significantly smoother side walls
 - ✓ More stable/rigid by better layer-by-layer adhesion than BMP
- BMP 2PP printing:
 - ✓ Yields sharper apexes of the structures
- Optimization of writing strategy of the very tip yields better results – top voxel (*subvoxel*) optimization
- Resulted radius of 100 nm



Characterization – 2/2, Coating

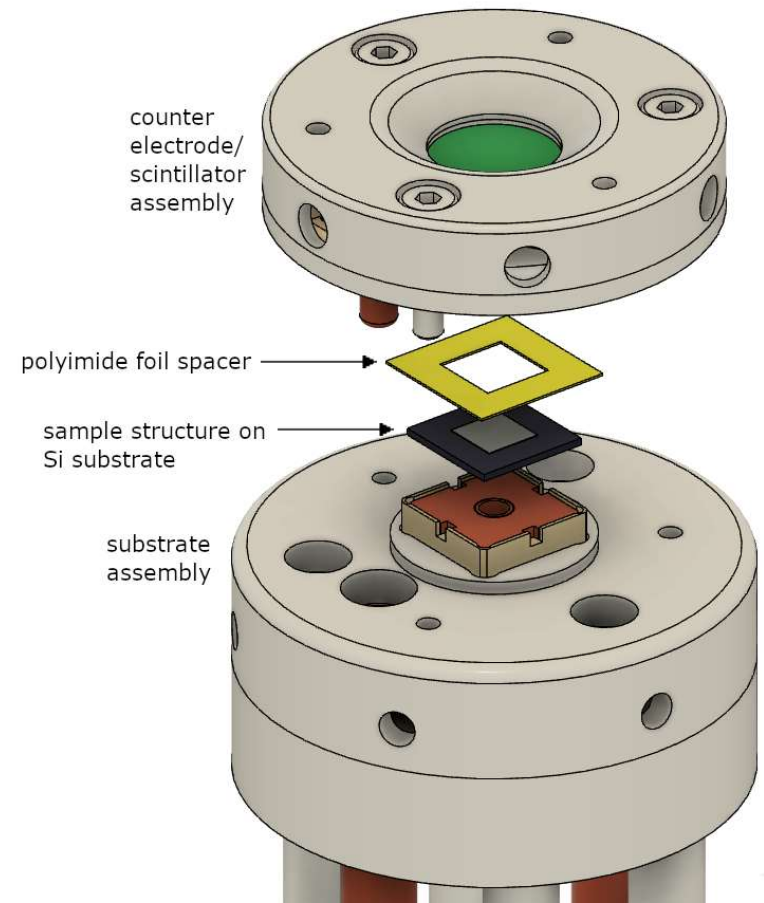
Magnetron sputter coating Au or Cr

- melting of the sample
- Introduces damage to the structures due to elevated temperature



FE Experiment – 1/3

- UHV compatible sample holder
(*designed by L.Dupák, ISI Brno*)
- Array of 10 x 10 square pyramids
on 8 x 8 mm Si chip
- Mounted in Diode configuration
- An 80 μm thick polyimide sheet spacer
separates the chip from the counter
electrode.
- The counter electrode/scintillator -
Ce:YAG scintillating monocrystal
coated with a 30 nm conductive Al
layer, connected to picoammeter



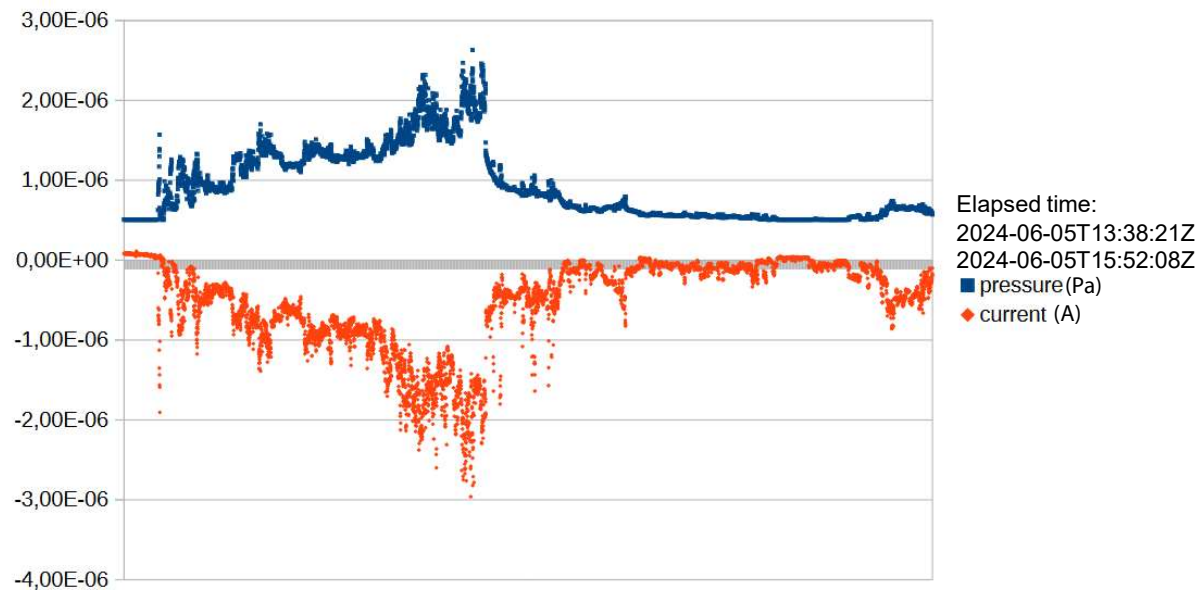
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FE Experiment – 2/3

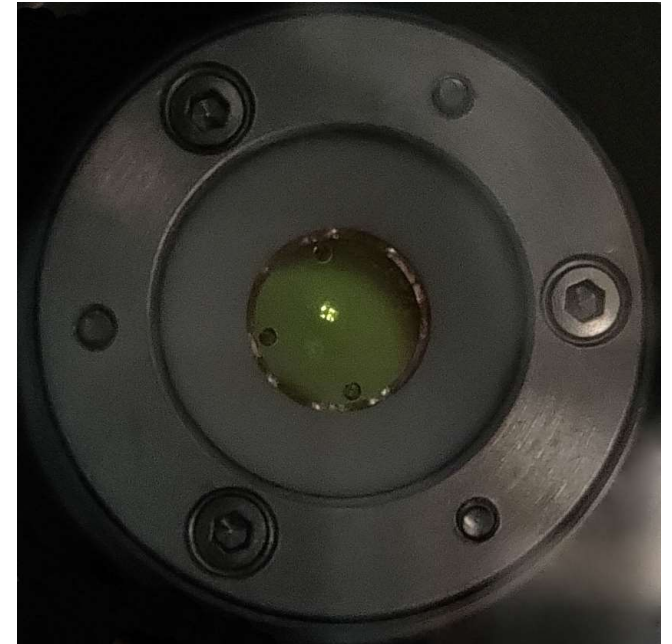
- Au 20nm/ 10 x 10 square pyramids
- Value of workfunction $\phi_{Au}=5.1$ eV
- UHV pressure prior experiment: $5 \cdot 10^{-7}$ Pa
- The distance between the tips of the array and the counter electrode is 25 to 30 μm .

FE Experiment – 3/3

- Au 20nm/ 10 x 10 square pyramids
- Switching of emission centres observed
- Fluctuation of current
- Suspecting micro discharges



ITG IVEW 2024



Future modifications

- Study of RIE thinning
 - To improve the overall sharpness of the structures

Seeking replacement for more suitable coating method:

- 2PP compatible with conventional photolithography
 - Electroforming
 - Electroless plating

Conclusions

- Planar 3D structures as a platform for future development
- Integration into other 3D printed devices: electrodes, octupoles, etc., *for newest development see IVNC2023 & IVNC2024*
- Emission occurred at high applied voltage,
- Micro discharges lead to decrease in performance
- 2PL resin compatible with Ultra-High Vacuum
- 2PL resin compatible with aggressive chemicals
- Magnetron sputtered metallic coating -> erosion, melting
- Future: Electroless plating/Conductive oxide deposition (ALD), 2PL+Electroforming



Thank you for your attention



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